

SOT1096-1

plastic ball grid array package; 452 balls

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	BGA452
Package type industry code	BGA452
Package style descriptive code	BGA (ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	144E
JEDEC package outline code	MS-034
Mounting method type	S (surface mount)
Issue date	14-11-2008

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	26.8	-	27	27.2	mm
E	package width	26.8	-	27	27.2	mm
A	seated height	2	-	2.25	2.45	mm
A ₂	package height	1.6	-	1.75	1.85	mm
n ₂	actual quantity of termination	-	-	452	-	



2. Package outline

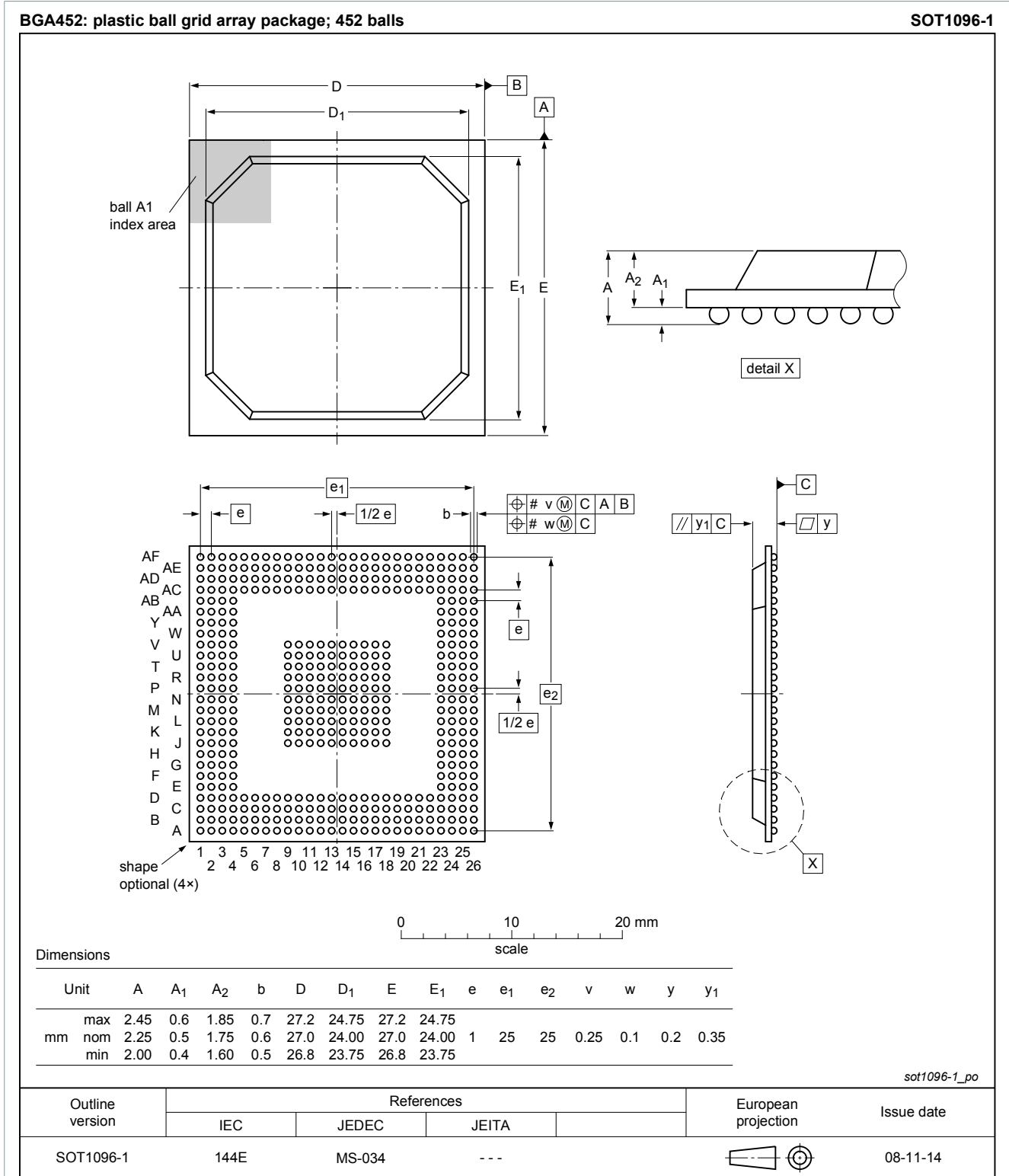


Fig. 1. Package outline BGA452 (SOT1096-1)

3. Legal information

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4. Contents

1. Package summary.....	1
2. Package outline.....	2
3. Legal information.....	3

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